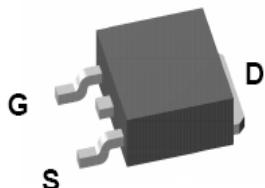


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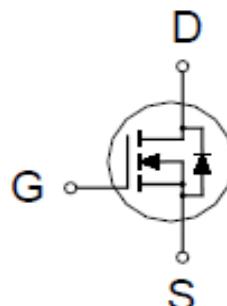
N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
650V	2.6Ω @ $V_{GS} = 10V$	4A



TO-252



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ²	I_D	4	A
		2.5	
Pulsed Drain Current ^{1, 2}	I_{DM}	15	
Avalanche Current ³	I_{AS}	2	
Avalanche Energy ³	E_{AS}	20	mJ
Power Dissipation	P_D	54	W
		21	
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.3	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Limited only by maximum temperature allowed.

³ $V_{DD} = 50V$, $L = 10mH$, starting $T_J = 25^\circ C$.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.5	3.3	4.5	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 30\text{V}$			± 100	
Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}, T_C = 25^\circ\text{C}$			1	μA
		$V_{\text{DS}} = 520\text{V}, V_{\text{GS}} = 0\text{V}, T_C = 100^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 2\text{A}$		2.1	2.6	Ω
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 15\text{V}, I_D = 2\text{A}$		2.5		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		512		pF
Output Capacitance	C_{oss}			52		
Reverse Transfer Capacitance	C_{rss}			12		
Total Gate Charge ²	Q_g	$V_{\text{DD}} = 520\text{V}, I_D = 4\text{A}, V_{\text{GS}} = 10\text{V}$		13		nC
Gate-Source Charge ²	Q_{gs}			3.8		
Gate-Drain Charge ²	Q_{gd}			4.3		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DD}} = 350\text{V}, I_D = 4\text{A}, R_G = 25\Omega$		27		nS
Rise Time ²	t_r			59		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			90		
Fall Time ²	t_f			74		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				4	A
Forward Voltage ¹	V_{SD}	$I_F = 4\text{A}, V_{\text{GS}} = 0\text{V}$			1	V
Reverse Recovery Time	t_{rr}	$I_F = 4\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		374		nS
Reverse Recovery Charge	Q_{rr}			2.1		μC

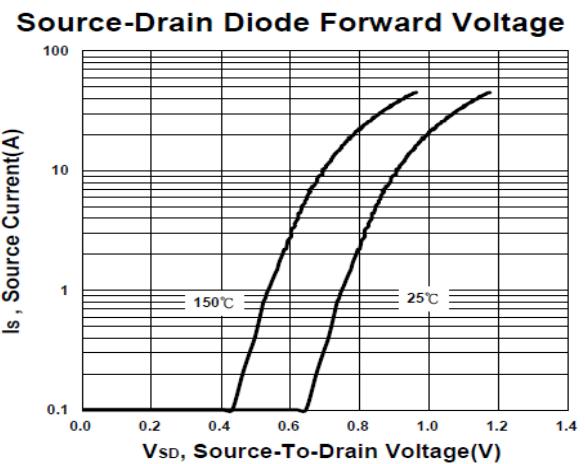
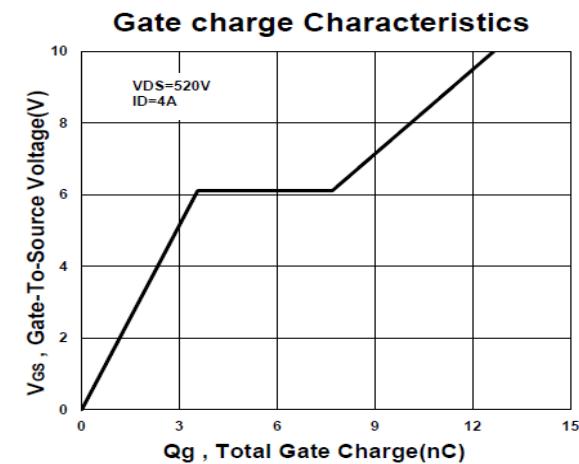
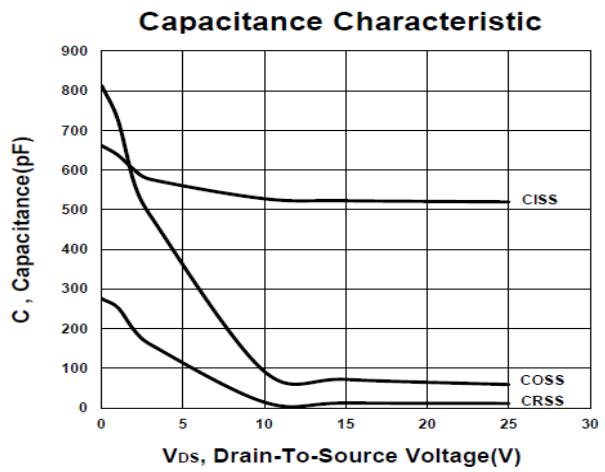
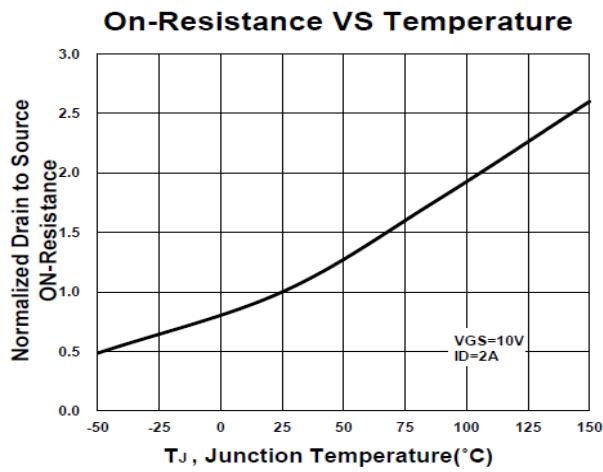
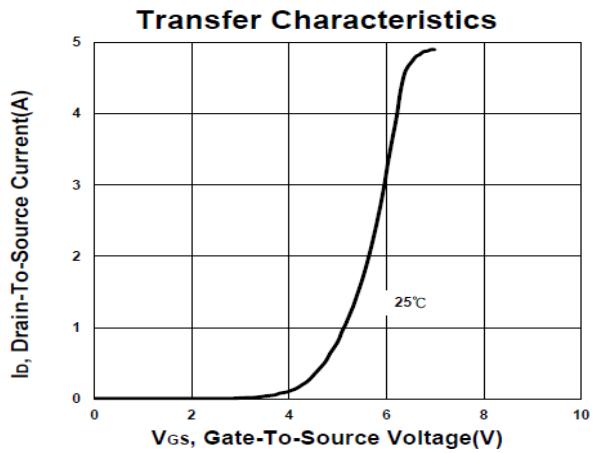
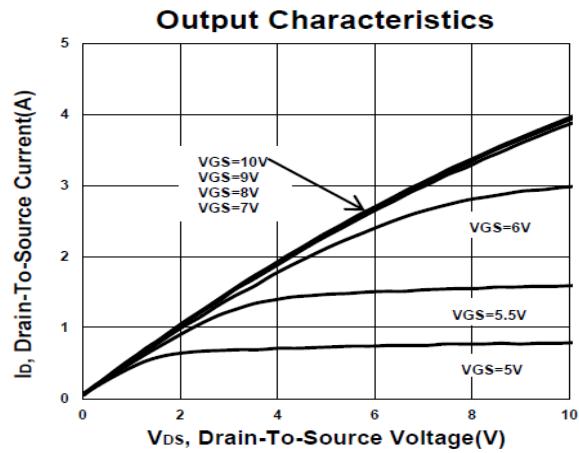
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

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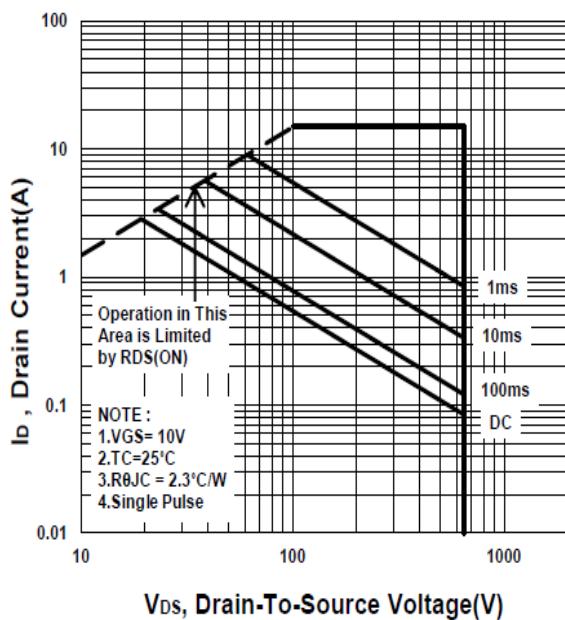
N-Channel Enhancement Mode MOSFET



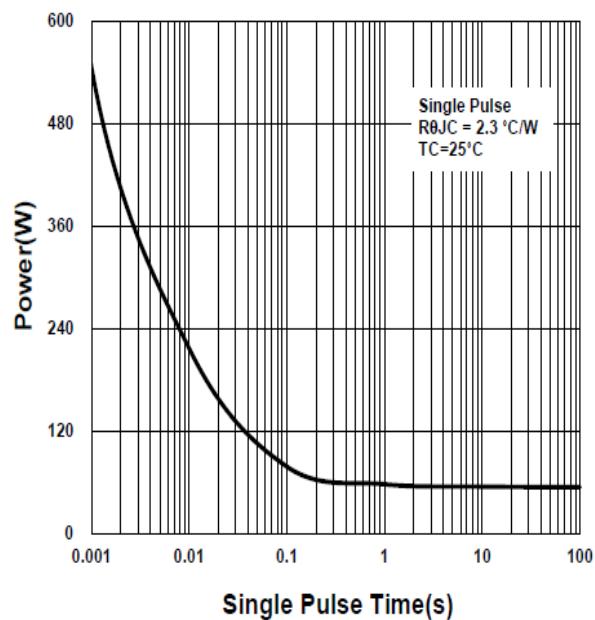
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N-Channel Enhancement Mode MOSFET

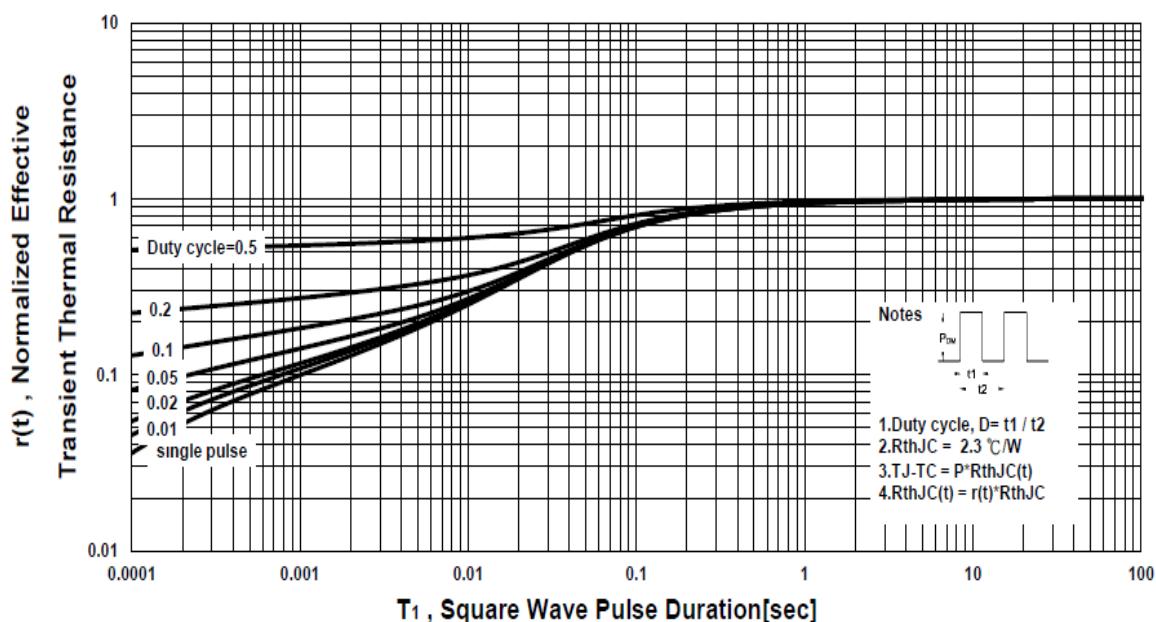
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



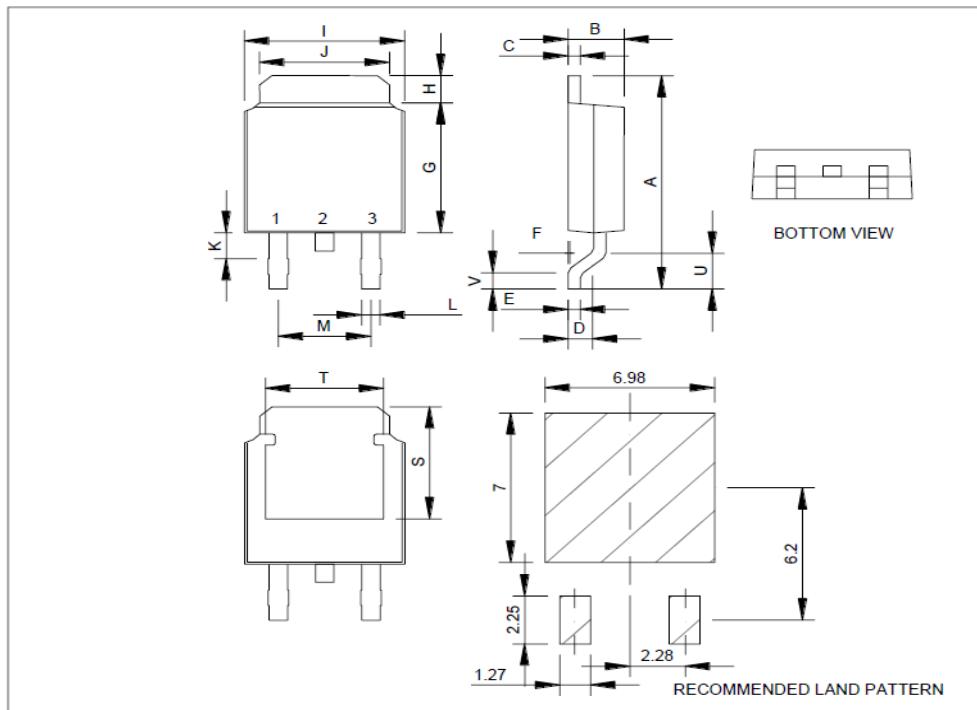
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N-Channel Enhancement Mode MOSFET

Package Dimension

TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	10	10.41	J	4.8		5.64
B	2.1	2.2	2.4	K	0.15		1.1
C	0.4	0.5	0.61	L	0.4	0.76	0.89
D	0.82	1.2	1.5	M	4.2	4.58	5
E	0.4	0.5	0.61	S	4.9	5.1	5.3
F	0		0.2	T	4.6	4.75	5.44
G	5.3	6.1	6.3	U	1.4		1.78
H	0.9		1.7	V	0.55	1.25	1.7
I	6.3	6.5	6.8				



*因为各家封装模具不同而外观略有差异，不影响电性及Layout。